

IN THE DRAWINGS:

Figures 4 and 8 have been amended. Figure 4 has been amended to show the deformation-interrupting section continuously extending through the buildup layer from the first conductor layer, through the first insulation layer and to the surface conductive layer (as described from page 21, line 17 to page 22, line 2 of the specification). Figure 8 has been amended to include the designation --Prior Art--. Replacement sheets having such changes are enclosed.

REMARKS

Reconsideration of this application, as amended, is respectfully requested.

In the Official Action, the Examiner objects to the Drawings because Figure 8 should be designated by a legend, such as --Prior Art-- since only that which is old is illustrated therein. In response, Figure 8 has been amended as suggested by the Examiner. A replacement sheet having the above-described amendment is enclosed. Accordingly, it is respectfully requested that the objection to the Drawings be withdrawn.

In the Official Action, the Examiner rejects claims 1, 4 and 5 under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,818,836 to Shiraishi (hereinafter "Shiraishi").

In response, independent claim 1 has been amended to clarify its distinguishing features. Specifically, claim 1 has been amended to recite "a deformation-interrupting section continuously extending through the buildup layer from the first conductor layer, through the first insulation layer and to the surface conductive layer." The amendment to claim 1 is fully supported in the original disclosure, particularly at Figure 4 of the Figures and from page 19, line 9 to page 23, line 6 and more particularly from page 21, line 17 to page 22, line 2. Thus, no new matter has been entered into the disclosure by way of the amendment to claim 1. Furthermore, the amendment to claim 1 is within the elected Species II directed to Figure 4.

Although the limitations added to claim 1 by the present amendment are fully supported in the original disclosure, they are not shown in the Figures. Therefore, Figure 4 has been amended to show the deformation-interrupting section continuously extending through the buildup layer from the first conductor layer, through the first insulation layer and to the surface conductive layer. Those of ordinary skill in the art would understand the

description from page 21, line 17 to page 22, line 2 of the specification to be illustrated as shown in amended Figure 4. Thus, no new matter has been entered into the disclosure by way of the amendment to Figure 4.

The circuit board as recited in claim 1 is directed to a core plate; a buildup layer formed on the core plate including at least a first insulation layer and a first conductor layer alternately stacked on each other; a surface conductive layer formed on the buildup layer and serving as a terminal electrode for connection to an electronic component; and the deformation-interrupting section discussed above. Claim 1 further recites that the deformation-interrupting section is formed of a material having a lower thermal expansion coefficient and a higher Young's modulus than the first insulation layer, the deformation-interrupting section interrupting deformation of the first insulation layer when there is a change in ambient temperature or an external force is applied to the circuit board.

Such a structure is not disclosed or suggested in Shiraishi. That is, Shiraishi discloses an electrically conductive paste 50 in a hole 24 that is only intended to achieve an electrical connection and is not provided to prevent deformation from occurring in the circuit board. Furthermore, although Shiraishi discloses the conductive paste being disposed in a hole, the same does not continuously extend through the buildup layer from the first conductor layer, through the first insulation layer and to the surface conductive layer. As discussed in the specification, such a configuration not only results in providing resistance to deformation caused by excessive heat or force, but does not require a solder-resist forming/removing process necessary for forming the interlevel insulator layers, further resulting in decreasing the cost and tact time required for production of the circuit board (see page 21, line 27 to page 22, line 4).

With regard to the rejection of claims 1, 4 and 5 under 35 U.S.C. § 102(e), a circuit board having the features discussed above and as recited in independent claim 1 is nowhere disclosed in Shiraishi. Since it has been decided that “anticipation requires the presence in a single prior art reference, disclosure of each and every element of the claimed invention, arranged as in the claim,”¹ independent claim 1 is not anticipated by Shiraishi. Accordingly, independent claim 1 patentably distinguishes over Shiraishi and is allowable. Claims 4 and 5 being dependent upon claim 1 is thus at least allowable therewith. Consequently, the Examiner is respectfully requested to withdraw the rejection of claims 1, 4 and 5 under 35 U.S.C. § 102(e).

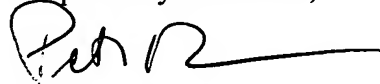
Furthermore, new claims 9-11 have been added to further define the patentable invention. New claims 9-11 are fully supported in the original disclosure. Thus, no new matter has been entered into the disclosure by way of the addition of new claims 9-11. Applicants respectfully submit that new claims 9-11 are at least allowable as depending upon an allowable base claim (1).

Lastly, by way of the present amendment, an error has been corrected in the specification. Specifically, “the insulative deformation-interrupting sections 12” at lines 8-9 of page 20 has been changed to --the insulative deformation-interrupting sections 13-- to be consistent with the Drawings at Figure 4. No new matter has been entered into the disclosure by way of such amendment.

¹ Lindeman Maschinenfabrik GMBH v. American Hoist and Derrick Company, 730 F.2d 1452, 1458; 221 U.S.P.Q. 481, 485 (Fed. Cir., 1984).

In view of the above, it is respectfully submitted that this application is in condition for allowance. Accordingly, it is respectfully requested that this application be allowed and a Notice of Allowance issued. If the Examiner believes that a telephone conference with Applicant's attorneys would be advantageous to the disposition of this case, the Examiner is requested to telephone the undersigned.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Peter I. Bernstein', with a long horizontal flourish extending to the right.

Peter I. Bernstein

Registration No. 43,497

Scully, Scott, Murphy & Presser, P.C.
400 Garden City Plaza, Suite 300
Garden City, New York 11530
(516) 742-4343

TS:cm

Encl. (Replacement Sheets For Figures 4 and 8)